

ABSTRACT

A semiconductor device (1) comprises a semiconductor chip (10), a substrate (20) which is formed with a interconnecting pattern (22), and a binder (30) which electrically connects the semiconductor chip (10) and the interconnecting pattern (22); the binder (30) forms a two-layer structure comprising a first layer (32) of which base material is a first resin and which is disposed on the side of the semiconductor chip (10), and a second layer (34) of which base material is a second resin and which is disposed on the side of the substrate (20); and the first resin and the second resin have different physical properties in the coefficients of thermal expansion, or the likes.